

MC14049UB

Hex Buffers

The MC14049UB hex inverter/buffer is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. This complementary MOS device finds primary use where low power dissipation and/or high noise immunity is desired. This device provides logic-level conversion using only one supply voltage, V_{DD} . The input-signal high level (V_{IH}) can exceed the V_{DD} supply voltage for logic-level conversions. Two TTL/DTL Loads can be driven when the device is used as CMOS-to-TTL/DTL converters ($V_{DD} = 5.0\text{ V}$, $V_{OL} \leq 0.4\text{ V}$, $I_{OL} \geq 3.2\text{ mA}$). Note that pins 13 and 16 are not connected internally on this device; consequently connections to these terminals will not affect circuit operation.

Features

- High Source and Sink Currents
- High-to-Low Level Converter
- Supply Voltage Range = 3.0 V to 18 V
- Meets JEDEC UB Specifications
- V_{IN} can exceed V_{DD}
- Improved ESD Protection on All Inputs
- These Devices are Pb-Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V_{in}	Input Voltage Range (DC or Transient)	-0.5 to +18.0	V
V_{out}	Output Voltage Range (DC or Transient)	-0.5 to V_{DD} +0.5	V
I_{in}	Input Current (DC or Transient) per Pin	± 10	mA
I_{out}	Output Current (DC or Transient) per Pin	+45	mA
P_D	Power Dissipation, per Package (Note 1)		mW
	Plastic	825	
	SOIC	740	
T_A	Ambient Temperature Range	-55 to +125	$^{\circ}\text{C}$
T_{stg}	Storage Temperature Range	-65 to +150	$^{\circ}\text{C}$
T_L	Lead Temperature (8-Second Soldering)	260	$^{\circ}\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating: All Packages: See Figure 4.

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields referenced to the V_{SS} pin, only. Extra precautions must be taken to avoid applications of any voltage higher than the maximum rated voltages to this high-impedance circuit. For proper operation, the ranges $V_{SS} \leq V_{in} \leq 18\text{ V}$ and $V_{SS} \leq V_{out} \leq V_{DD}$ are recommended.

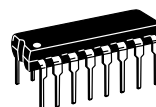
Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



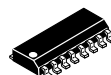
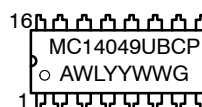
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MARKING DIAGRAMS



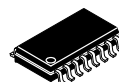
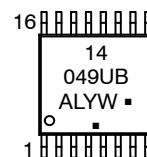
PDIIP-16
P SUFFIX
CASE 648



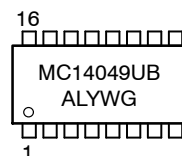
SOIC-16
D SUFFIX
CASE 751B



TSSOP-16
DT SUFFIX
CASE 948F



SOEIAJ-16
F SUFFIX
CASE 966



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

MC14049UB

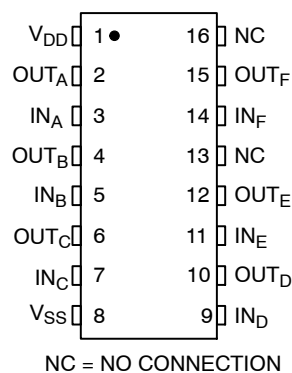


Figure 1. Pin Assignment

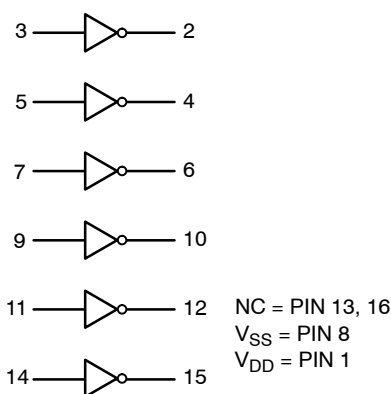


Figure 2. Logic Diagram
MC14049UB

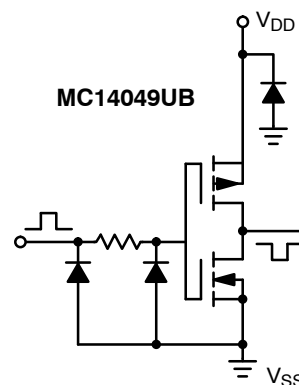


Figure 3. Circuit Schematic
(1/6 of circuit shown)

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V _{DD} Vdc	- 55°C		25°C			125°C		Unit	
			Min	Max	Min	Typ (Note 2)	Max	Min	Max		
Output Voltage V _{in} = V _{DD} or 0	“0” Level	V _{OL}	5.0	-	0.05	-	0	0.05	-	0.05	Vdc
			10	-	0.05	-	0	0.05	-	0.05	
V _{in} = 0 or V _{DD}	“1” Level	V _{OH}	5.0	4.95	-	4.95	5.0	-	4.95	-	Vdc
			10	9.95	-	9.95	10	-	9.95	-	
Input Voltage (V _O = 4.5 Vdc) (V _O = 9.0 Vdc) (V _O = 13.5 Vdc)	“0” Level	V _{IL}	5.0	-	1.0	-	2.25	1.0	-	1.0	Vdc
			10	-	2.0	-	4.50	2.0	-	2.0	
			15	-	2.5	-	6.75	2.5	-	2.5	
(V _O = 0.5 Vdc) (V _O = 1.0 Vdc) (V _O = 1.5 Vdc)	“1” Level	V _{IH}	5.0	4.0	-	4.0	2.75	-	4.0	-	Vdc
			10	8.0	-	8.0	5.50	-	8.0	-	
			15	12.5	-	12.5	8.25	-	12.5	-	
Output Drive Current (V _{OH} = 2.5 Vdc) (V _{OH} = 9.5 Vdc) (V _{OH} = 13.5 Vdc)	Source	I _{OH}	5.0	-1.6	-	-1.25	-2.5	-	-1.0	-	mAdc
			10	-1.6	-	-1.3	-2.6	-	-1.0	-	
(V _{OL} = 0.4 Vdc) (V _{OL} = 0.5 Vdc) (V _{OL} = 1.5 Vdc)	Sink	I _{OL}	5.0	3.75	-	3.2	6.0	-	2.6	-	mAdc
			10	10	-	8.0	16	-	6.6	-	
			15	30	-	24	40	-	19	-	
Input Current		I _{in}	15	-	±0.1	-	±0.000 01	±0.1	-	±1.0	μAdc
Input Capacitance (V _{in} = 0)		C _{in}	-	-	-	-	10	20	-	-	pF
Quiescent Current (Per Package)		I _{DD}	5.0	-	1.0	-	0.002	1.0	-	30	μAdc
			10	-	2.0	-	0.004	2.0	-	60	
			15	-	4.0	-	0.006	4.0	-	120	
Total Supply Current (Note 3 and 4) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, all buffers switching)		I _T	5.0	I _T = (1.8 μA/kHz) f + I _{DD}						μAdc	
			10	I _T = (3.5 μA/kHz) f + I _{DD}							
			15	I _T = (5.3 μA/kHz) f + I _{DD}							

2. Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.

3. The formulas given are for the typical characteristics only at 25°C.

4. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) Vfk$$

where: I_T is in μA (per package), C_L in pF, V = (V_{DD} - V_{SS}) in volts, f in kHz is input frequency, and k = 0.002.

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SWITCHING CHARACTERISTICS (Note 5) ($C_L = 50$ pF, $T_A = 25^\circ\text{C}$)

Characteristic	Symbol	V_{DD} Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise Time $t_{TLH} = (0.8 \text{ ns/pF}) C_L + 60 \text{ ns}$ $t_{TLH} = (0.3 \text{ ns/pF}) C_L + 35 \text{ ns}$ $t_{TLH} = (0.27 \text{ ns/pF}) C_L + 26.5 \text{ ns}$	t_{TLH}	5.0 10 15	- - -	100 50 40	160 100 60	ns
Output Fall Time $t_{THL} = (0.3 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{THL} = (0.12 \text{ ns/pF}) C_L + 14 \text{ ns}$ $t_{THL} = (0.1 \text{ ns/pF}) C_L + 10 \text{ ns}$	t_{THL}	5.0 10 15	- - -	40 20 15	60 40 30	ns
Propagation Delay Time $t_{PLH} = (0.38 \text{ ns/pF}) C_L + 61 \text{ ns}$ $t_{PLH} = (0.20 \text{ ns/pF}) C_L + 30 \text{ ns}$ $t_{PLH} = (0.11 \text{ ns/pF}) C_L + 24.5 \text{ ns}$	t_{PLH}	5.0 10 15	- - -	80 40 30	120 65 50	ns
Propagation Delay Time $t_{PHL} = (0.38 \text{ ns/pF}) C_L + 11 \text{ ns}$ $t_{PHL} = (0.12 \text{ ns/pF}) C_L + 9 \text{ ns}$ $t_{PHL} = (0.11 \text{ ns/pF}) C_L + 4.5 \text{ ns}$	t_{PHL}	5.0 10 15	- - -	30 15 10	60 30 20	ns

5. The formulas given are for the typical characteristics only at 25°C .

6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

ORDERING INFORMATION

Device	Package	Shipping†
MC14049UBCPG	PDIP-16 (Pb-Free)	500 Units / Tape & Ammunition Box
MC14049UBDG	SOIC-16 (Pb-Free)	48 Units / Rail
NLV14049UBDG*		
MC14049UBDR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
NLV14049UBDR2G*		
MC14049UBDTELG	TSSOP-16 (Pb-Free)	96 Units / Rail
MC14049UBDTR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel
MC14049UBFELG	SOEIAJ-16 (Pb-Free)	2000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

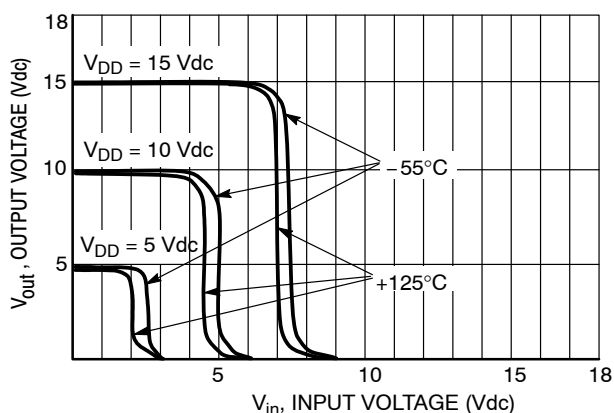


Figure 4. Typical Voltage Transfer Characteristics versus Temperature

MC14049UB

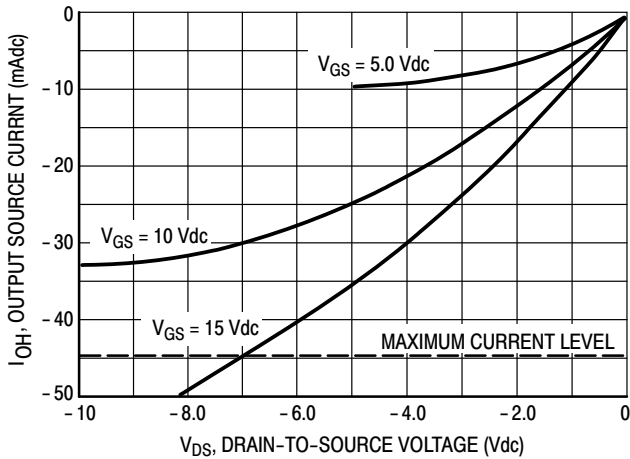
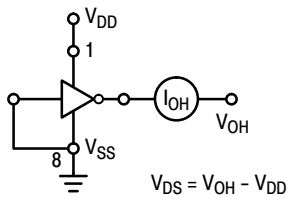


Figure 5. Typical Output Source Characteristics

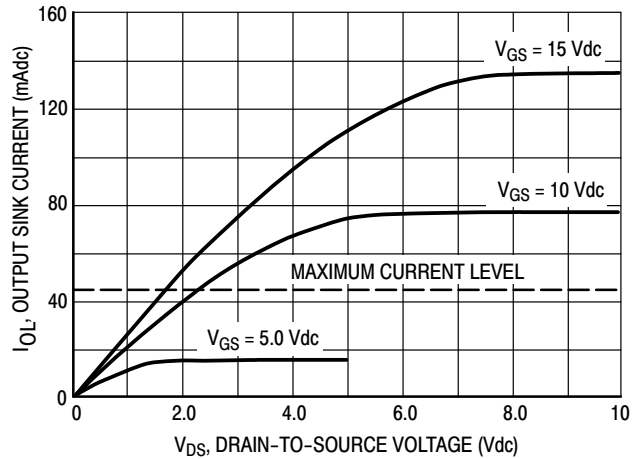
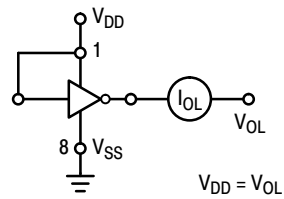


Figure 6. Typical Output Sink Characteristics

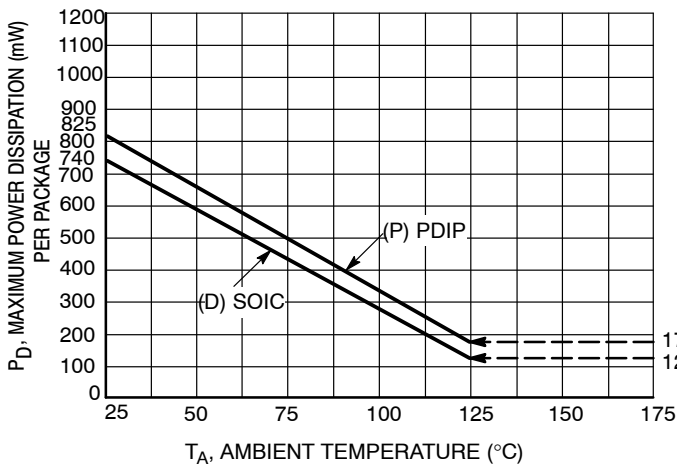


Figure 7. Ambient Temperature Power Derating

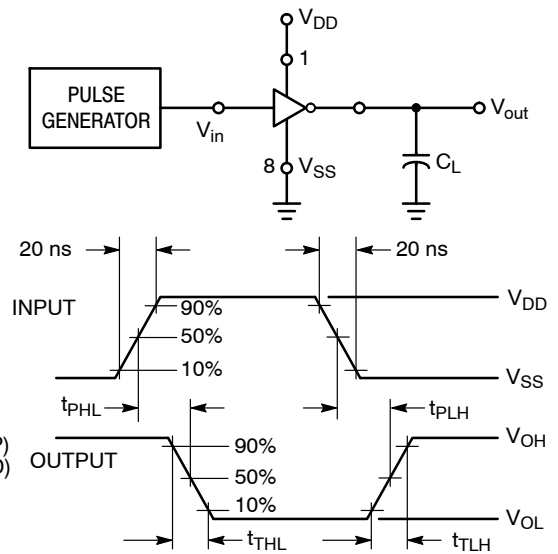
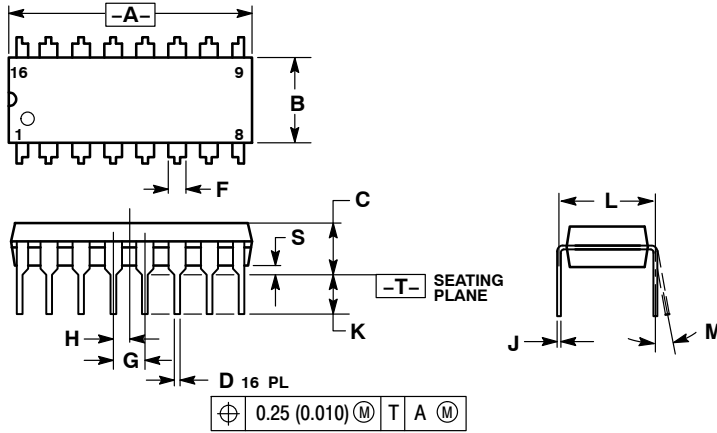


Figure 8. Switching Time Test Circuit and Waveforms

MC14049UB

PACKAGE DIMENSIONS

PDIP-16
P SUFFIX
PLASTIC DIP PACKAGE
CASE 648-08
ISSUE T



NOTES:

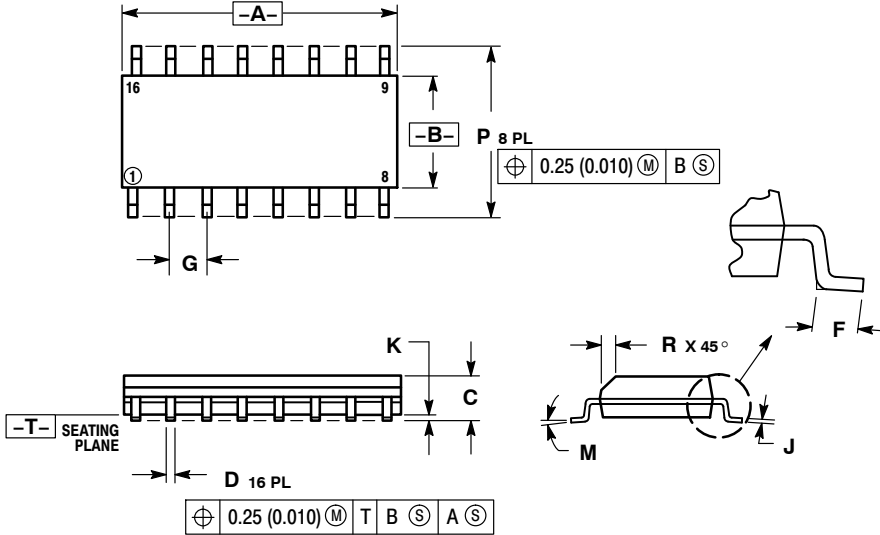
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

MC14049UB

PACKAGE DIMENSIONS

SOIC-16
D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751B-05
ISSUE K

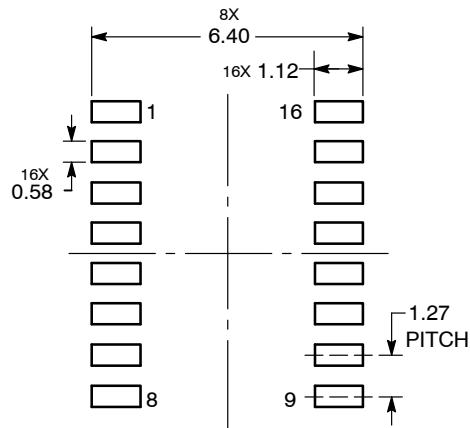


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0° - 7°		0° - 7°	
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

SOLDERING FOOTPRINT*



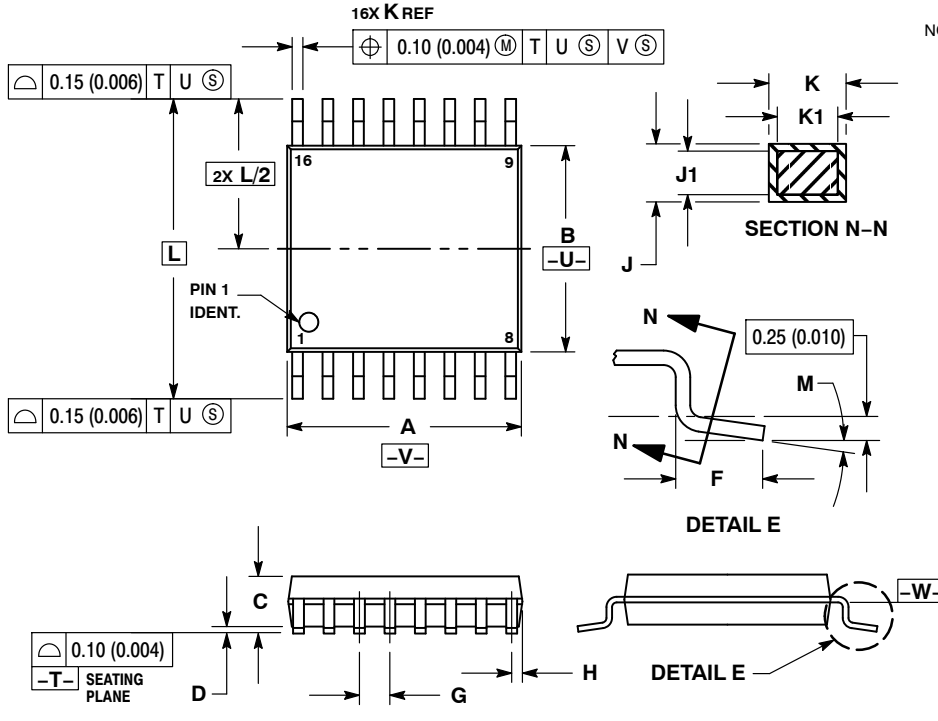
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC14049UB

PACKAGE DIMENSIONS

TSSOP-16
DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948F-01
ISSUE B

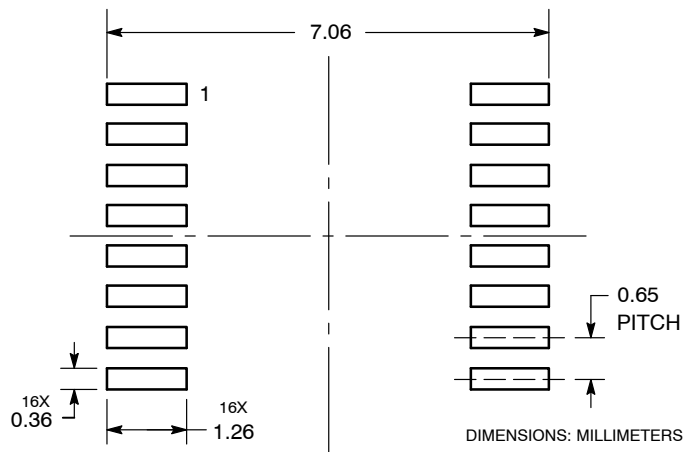


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT*

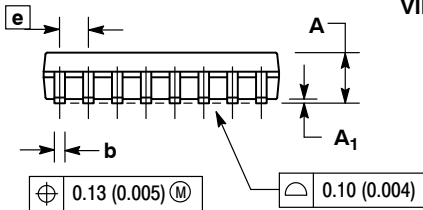
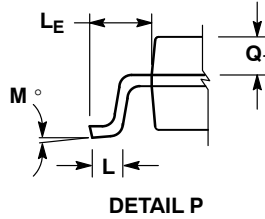
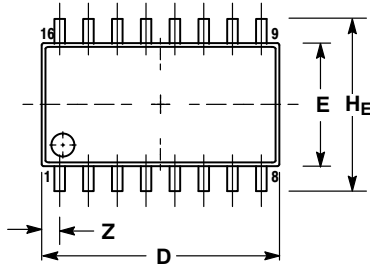


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC14049UB

PACKAGE DIMENSIONS

SOEIAJ-16
F SUFFIX
PLASTIC EIAJ SOIC PACKAGE
CASE 966-01
ISSUE A



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q ₁	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

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